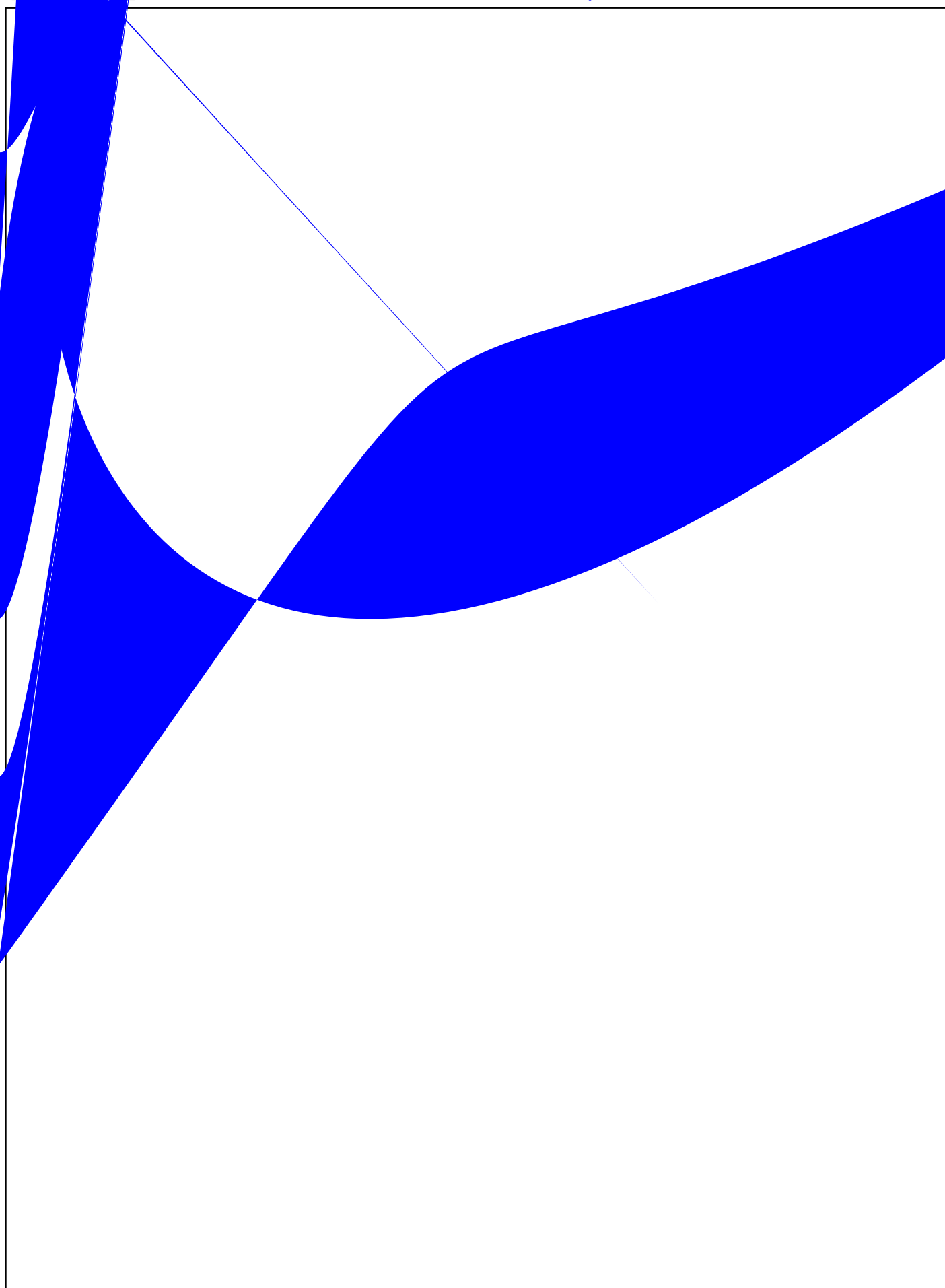








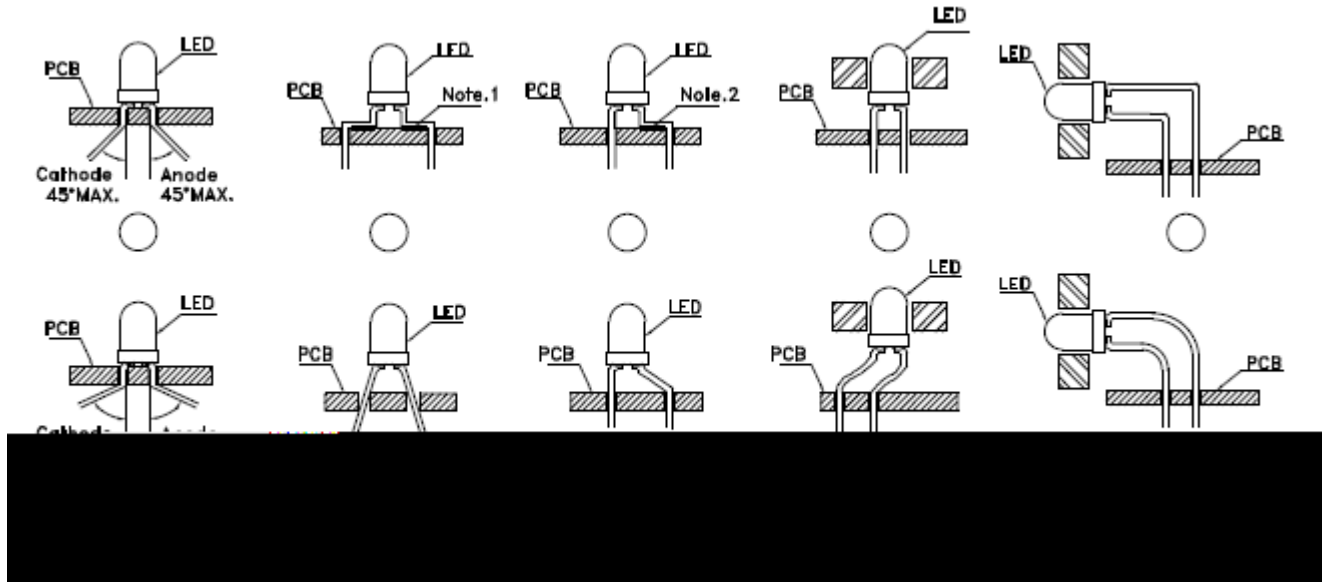
Infrared Photo Diode Specification

- Commodity: Infrared Photo diode
- Intensity Bin Limits (VR=5V, Ee=1mW/cm², =940nm)

BIN CODE	Min.(uA)	Max.(uA)
36	53	64
37	64	77
38	77	92

LED MOUNTING METHOD

- The lead pitch of the LED must match the pitch of the mounting holes on the PCB during component placement. Lead-forming may be required to insure the lead pitch matches the hole pitch. Refer to the figure below for proper lead forming procedures (Fig.1).



ounting method

Note 1-2: Do not route PCB trace in the contact area between the lead frame and the PCB to prevent short-circuits.

- When soldering wire to the LED, use individual heat-shrink tubing to insulate the exposed leads to prevent accidental contact short-circuit (Fig.2).

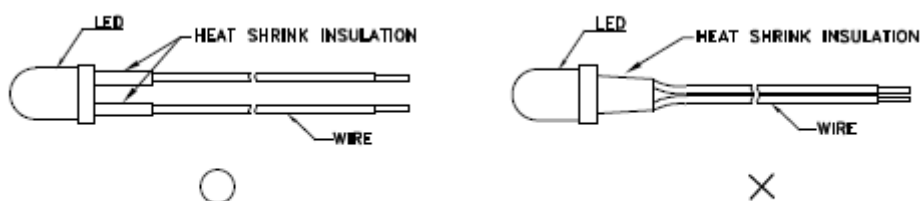
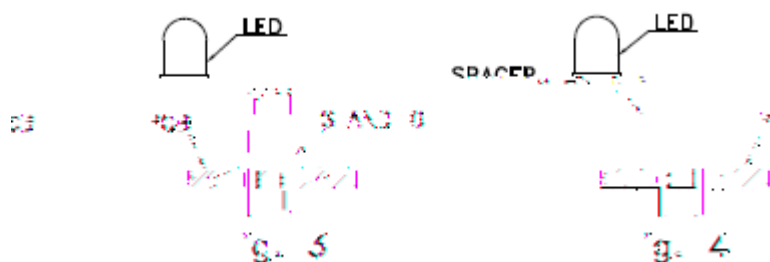
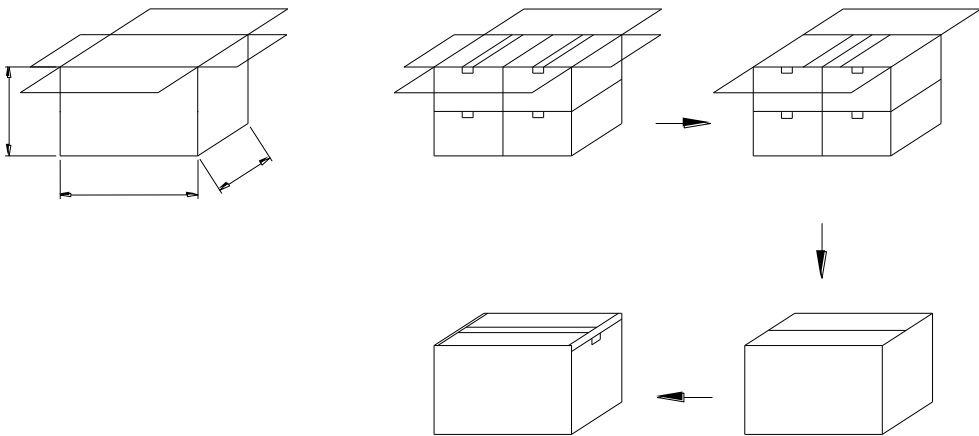
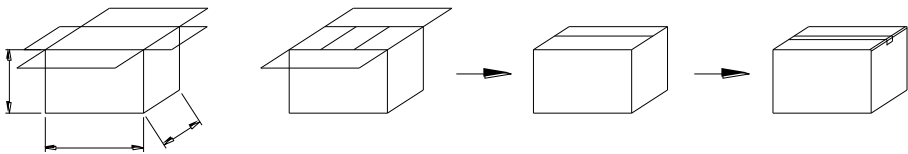
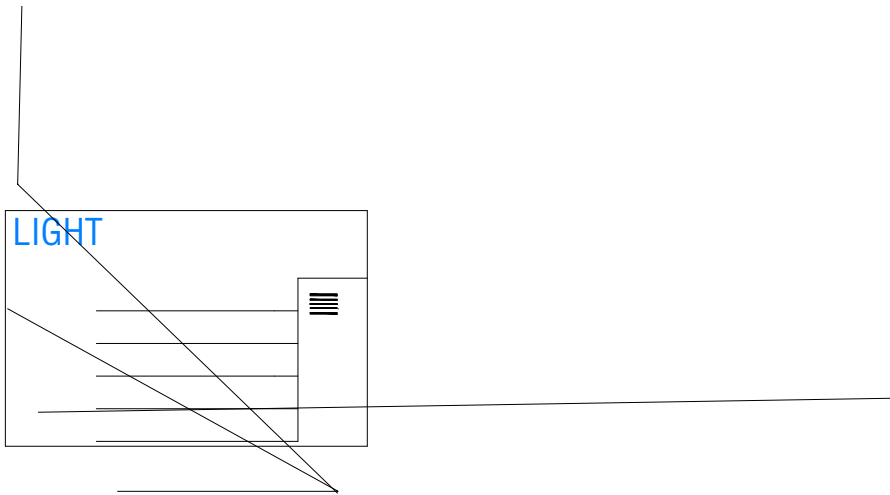


Fig. 2

- Use stand-offs (Fig.3) or spacers (Fig.4) to securely position the LED above the PCB.



PACKAGE



Bag minimum volume (pcs / Bag)	Bag volume (pcs / Bag)	Inner box volume (Bag / box)	Outer carton volume (Box / Carton)
500	1000	10	4